Silicon N-Channel MOS FET

HITACHI

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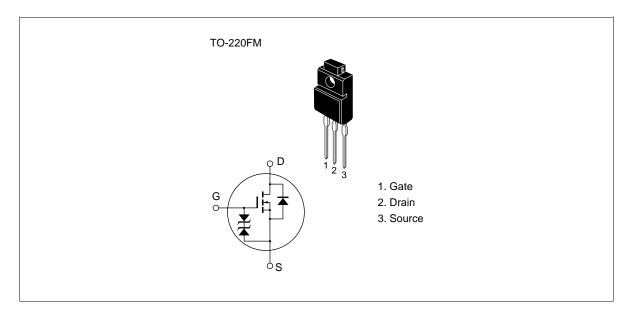
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline





Absolute Maximum Ratings (Ta = 25° C)

Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1566	V _{DSS}	450	V
	2SK1567		500	
Gate to source voltage		V _{GSS}	±30	V
Drain current		I _D	7	A
Drain peak current		L *1 D(pulse)	28	A
Body to drain diode reverse	e drain current	I _{DR}	7	A
Channel dissipation		Pch*2	35	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

Note 1. PW 10 µs, duty cycle 1%

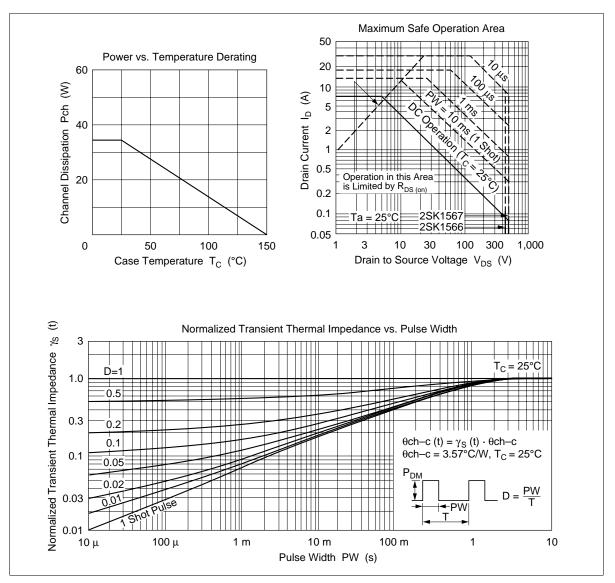
2. Value at $T_c = 25^{\circ}C$

Electrical Characteristics (Ta = 25°C)

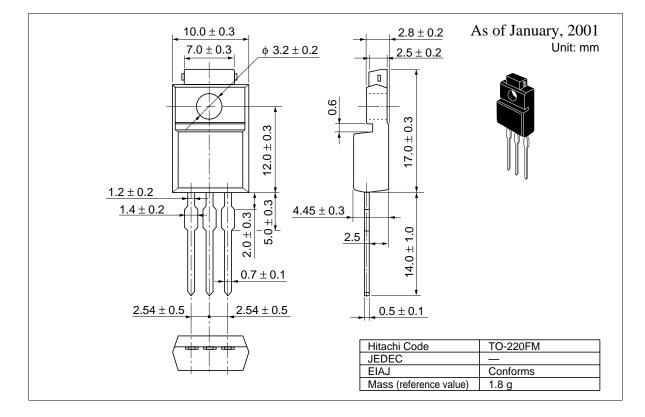
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1566	$V_{(BR)DSS}$	450	_	_	V	$I_{\rm D} = 10 \text{ mA}, V_{\rm GS} = 0$
breakdown voltage	2SK1567		500	_			
Gate to source breakdown voltage		$V_{(\text{BR})\text{GSS}}$	±30	_	—	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak cu	urrent	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1566	I _{DSS}	_	_	250	μA	$V_{\rm DS} = 360 \text{ V}, V_{\rm GS} = 0$
drain current	2SK1567						$V_{\rm DS} = 400 \text{ V}, \text{ V}_{\rm GS} = 0$
Gate to source cutoff	voltage	$V_{\text{GS(off)}}$	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Static Drain to source	2SK1566		_	0.6	0.8		$I_{\rm D} = 4$ A, $V_{\rm GS} = 10$ V * ¹
on state resistance	2SK1567		—	0.7	0.9	_	
Forward transfer admi	ittance	yfs	4.0	6.5	_	S	$I_{\rm D} = 4$ A, $V_{\rm DS} = 10$ V * ¹
Input capacitance		Ciss	—	1050	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	—	280	—	pF	f = 1 MHz
Reverse transfer capacitance		Crss	—	40	—	pF	_
Turn-on delay time		t _{d(on)}	—	15	—	ns	$I_{D} = 4 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		t,	—	55	—	ns	R _L = 7.5
Turn-off delay time		t _{d(off)}	_	95	_	ns	_
Fall time		t _f	_	40	—	ns	_
Body to drain diode fo voltage	rward	V_{DF}	—	0.95	_	V	$I_{F} = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time		t _{rr}	—	320	—	ns	$I_{F} = 7 \text{ A}, V_{GS} = 0,$ $di_{F}/dt = 100 \text{ A}/\mu\text{s}$

Note 1. Pulse test

See characteristic curves of 2SK1157, 2SK1158.



Package Dimensions



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